

NOVASTACK® 35-P HIGH CONDUCTIVITY TYPE

Part No. Plug:20708-0**E-01 Receptacle:20709-0**E-01

Product Specification

Qualification Test Report No. TR-16143

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4	S21601	November 18, 2021	Haji.Takahashi	S.Suzuki	Y.Hashimoto
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1. Scope

This Product Specification defines the test conditions and the performances of the NOVASTACK 35-P (HIGH CONDUCTIVITY TYPE) Connector, a board-to-board connector of 0.35 mm contact pitch.

2. Product Name and Parts No.

2.1 Product Name

NOVASTACK 35-P

2.2 Parts No.

Plug: 20708-0**E-01 Receptacle: 20709-0**E-01

3. Rating

3.1 Operating Conditions

Amperage: Signal contact ... 0.3A AC/DC (per contact pin)

12.0A AC/DC (total)

1.0A AC/DC (Per contact of up to 8 pins)

Power contact ... 2.0A AC/DC (per contact pin)

4.0A AC/DC (total)

Voltage: 50V AC(r.m.s.) /DC

Operating Temperature: 233 to 358K(-40°C to +85°C) (Containing temperature rise by current)

Operating Humidity: 85% MAX.

3.2 Storage Conditions

Storage Temperature : 248 to 333K(-25°C to 60°C) Storage Humidity : 85% MAX. (Non-condensing)

4. Test and Performance

Test Condition

This initial test is equal to it's at shipping condition and unless otherwise specified, all tests and measurements shall be performed under the following conditions in accordance with MIL-STD-202G.

Temperature ... 288K to 308K (15°C to 35°C)

Pressure ... 866hPa to 1066hPa (650mmHg to 800mmHg)

Relative Humidity ... 45 to 75%R.H.

4.1. Electrical Performance

Contact resistance	
Reference standard:	MIL-STD-202G, Method 307
Test conditions:	Solder the receptacle connector to the test board and mate the plug connector together, then measure the contact resistance as shown in Fig.2 by the four terminal methods. Apply the low level condition of 20mV MAX. DC for the open circuit voltage and 10mA MAX. DC for the closed circuit current.
Pass criteria:	Contact Initial: $30m\Omega MAX$. After testing: $\angle R20m\Omega MAX$. Power contact Initial: $30m\Omega MAX$. After testing: $\angle R20m\Omega MAX$.

2. Insulation resistance	
Reference standard:	MIL-STD-202G, Method 302
Test conditions:	Mate the plug and receptacle connector together, and then apply DC 250 V between the inner contact and the ground contact.
Pass criteria:	Initial : 1,000 M Ω MIN. After testing : 500 M Ω MIN.

3. Dielectric withstanding voltage		
Reference standard:	MIL-STD-202G, Method 301	
Test conditions:	Mate the receptacle and plug connector together, then apply AC 200V(rms) between the neighboring contacts for	
	a minute.	
Pass criteria:	No abnormalities such as creeping discharge, flashover, insulator breakdown occur.	

4.Temperature rising	
Reference standard:	-
Test conditions:	Mate the plug and receptacle connector together, then apply rating current per contact pin.
	a. Pin count 40P MAX.
	Signal contact0.3A per pin
	Power contact2.0A
	Pin count 42P MIN.
	Signal contact(12 /pin count) A per pin
	Power contact2.0A
	b. Pin count 20P MAX.
	Signal contact1A×8pin
	Other Signal contact0.3A per pin
	Power contact2.0A
	Pin count 22P MIN.
	Signal contact1A×8pin
	Other Signal contact4 /(pin count -8)A per pin
	Power contact2.0A
Pass criteria:	Over ambient ∠T30 °C MAX.

4.2. Mechanical Performance

1. Mating force and Unmating force		
Reference standard:	-	
Test conditions:	Solder the receptacle connector to the test board, then place the board and plug on push-on/pull-off machine, measure of initial and mating/unmating 20 cycles at a speed 25±3mm/min. along the mating axis.	
Pass criteria:	Mating Initial: to 28P 2.0 N/Pin MAX. 30P to 1.0 N/Pin MAX. Unmating 20cycles: to 28P 0.30 N/Pin MIN. 30P to 0.15 N/Pin MIN.	

2. Durability		
Reference standard:	-	
Test conditions:	Solder the receptacle connector to the test board, then place the board and plug on the push-on/pull-off machine, and repeat mating and unmating 20 cycles at a speed 25±3mm/min. along the mating axis.	
Pass criteria:	Contact resistance: Shall meet4.1.1	

3.Contact retention force		
Reference standard:	-	
Test conditions:	Place the connector on the push-on/pull-off machine, then apply force on the contact head and push the contact along the direction opposite to the contact insertion at a speed of 25±3mm/min. Measure the force when the contact dislodges the connector.	
Pass criteria:	Receptacle contact retention force: 0.1N MIN.	

4. Vibration	
Reference standard:	MIL-STD-202G, Method 201A
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and place them on the vibrator. Then apply the following vibration. During the testing, run 100mA DC to check electrical discontinuity.
	Frequency: 10Hz→55Hz→10Hz/approx 1min. Directions: Three mutually perpendicular direction. Total Amplitude: 1.52 mm Sweep duration: 2 hours for each direction, a total of 6 hours.
Pass criteria:	Contact resistance: Shall meet 4.1.1. Electrical discontinuity: No electrical discontinuity greater than 1µs shall occur. Appearance: No abnormality adversely affecting the performance shall occur.

5.Shock	
Reference standard:	MIL-STD-202G, Method 213B, Condition A.
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and place them on the shock machine. The n apply the following shock. MAX.G: 50G Duration: 11 milliseconds Wave Form: Half Sinusoidal Directions, cycle: 6 mutually perpendicular direction, 3 cycles about each direction
Pass criteria:	Contact resistance: Shall meet 4.1.1. Electrical discontinuity: No electrical discontinuity greater than 1µs shall occur. Appearance: No abnormality adversely affecting the performance shall occur.

4.3. Environmental Performance

1. Thermal shock	
Reference standard:	MIL-STD-202G, Method 107G, Condition A.
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 218K(-55°C): 30 min.→358K(85°C): 30 min. Transition time: 5 min. MAX. No. of cycles: 5 cycles
Pass criteria:	Contact resistance: Shall meet 4.1.1. Insulation resistance: Shall meet 4.1.2. Dielectric withstanding voltage: Shall meet 4.1.3. Appearance: No abnormality adversely affecting the performance shall occur.

2. High temperature life	
Reference standard:	MIL-STD-202G, Method 108A, Condition B.
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 358±2K (85±2°C) Duration: 250 hours
Pass criteria:	Contact resistance: Shall meet 4.1.1. Appearance: No abnormality adversely affecting the performance shall occur.

3. Low temperature life	
Reference standard:	-
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment . Temperature: 228±2K (-45±2°C) Duration: 96 hours
Pass criteria:	Contact resistance: Shall meet 4.1.1. Appearance: No abnormality adversely affecting the performance shall occur.

4. Humidity(Steady state)										
Reference standard:	MIL-STD-202G, Method 103B, Condition A.									
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 313±2K (40±2°C) Humidity: 90 to 95%RH Duration: 240 hours									
Pass criteria:	Contact resistance: Shall meet 4.1.1. Insulation resistance: Shall meet 4.1.2. Dielectric withstanding voltage: Shall meet 4.1.3. Appearance: No abnormality adversely affecting the performance shall occur.									

4.3. Environmental Performance

5. Humidity(Cycling)									
Reference standard:	MIL-STD-202G, Method 106G.								
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 298[263] to 338K (25[-10] to 65°C) Humidity: 90 to 98%RH Duration: 10cycles (240hours)								
Pass criteria:	Contact resistance: Shall meet 4.1.1. Insulation resistance: Shall meet 4.1.2. Dielectric withstanding voltage: Shall meet 4.1.3. Appearance: No abnormality adversely affecting the performance shall occur.								

6. Salt water spray										
Reference standard:	MIL-STD-202G, Method 101E, Condition B.									
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 308±2K (35±2°C) Salt water density: 5±1% [by weight] Duration: 48 hours									
Pass criteria:	Contact resistance: Shall meet 4.1.1. Appearance: No abnormality adversely affecting the performance shall occur.									

7. H₂S gas	
Reference standard:	-
Test conditions:	Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment. Temperature: 313±2K (40±2°C) Relative humidity: 80±5%RH Gas: H2S 3±1ppm Duration: 48 hours
Pass criteria:	Contact resistance: Shall meet 4.1.1. Appearance: No abnormality adversely affecting the performance shall occur.

4.4. Others

1. Solder ability	
Reference standard:	MIL-STD-202G, Method 208H.
Test conditions:	Dip the solder tine of the contact in the solder bath at 518±5K (245±5°C) for
	5±0.5 seconds after immersing the tine in the flux of RMA or R type for 5 to 10 seconds.
Pass criteria:	More than 95% of the dipped surface shall be evenly wet.

2. Soldering heat resistance							
Reference standard: -							
Test conditions:	Reflow temperature as shown in Fig.1.						
	The number of times of Reflow is within 3.						
Pass criteria:	No abnormality adversely affecting the performance shall not occur.						

3. Soldering iron	
Reference standard:	-
Test conditions:	Operating temperature : 613 to 633K (350°C±10)
	Application time of soldering iron : 5±1sec.
	The number of times of application : 3 times
Pass criteria:	No abnormality adversely affecting the performance shall occur.

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4.5 Test Sequence and Specimen Quantity

Table 1 Test Sequence and Sample Quantity

Test Item	Group													
	Α	В	С	D	Е	F	G	Н	J	K	L	М	N	Р
Contact Resistance		2,6		1,3,5	1,5	1,3	1,3	1,5	1,5	1,3	1,3			
Insulation Resistance					2,6			2,6	2,6					
D. W. Voltage					3,7			3,7	3,7					
Temperature rising	1													
Mating Force		1,5												
Unmating Force		3,7												
Durability		4												
Contact Retention Force			1											
Vibration				2										
Shock				4										
Thermal Shock					4									
High Temperature Life						2								
Low Temperature Life							2							
Humidity (Steady State)								4						
Humidity (Cycling)									4					
Salt Water Spray										2				
H2S Gas											2			
Solder ability												1		
Soldering Heat Resistance													1	
Soldering iron														1
Sample QTY.	5	5	20	5	5	5	5	5	5	5	5	10	10	10
	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.	pcs.

XNumbers indicate sequence in which tests are performed.

5. Reflow Temperature Profile

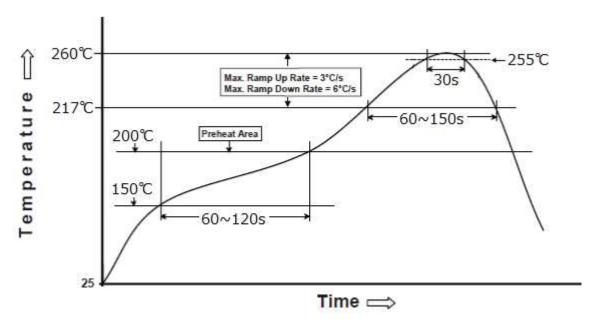


Fig.1 Reflow Temperature Profile

5.1 Recommended Metal Mask

Refer to DWG NO.20708 (Plug), 20709(Receptacle) .

6. Measuring method

6.1 Measuring method of Contact Resistance

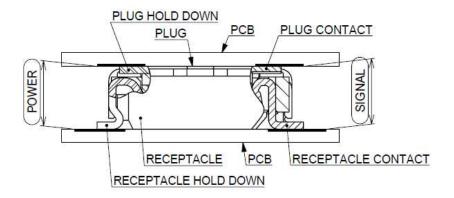


Fig.2 Contact Resistance